



## Declaration of Conformity to EU RoHS Directive 2011/65/EU

<b>GE Power Electronics Part Number:</b>	<b>Micro-BDCBB</b>
<b>Product Description:</b>	<b>DC Battery Distribution Circuit Breaker Bay</b>

This is to certify that the parts/products listed above meet the following materials requirements of the **RoHSII Directive 2011/65/EU**, as amended. The part numbers above that GE Power Electronics has identified as RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annex of the RoHS Directive. Note that any exemptions taken in this case would not include application specific exemptions (e.g. RoHS exemption 7b -lead in solder for network infrastructure) as GE Power Electronics cannot determine where products will be used.

GE Power Electronics assumes no responsibility to determine whether Customer's use of these products is covered under any RoHS exemptions.

The above information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreement terms between GE Power Electronics (or its affiliated companies) and its customers.

<b>EU RoHS Restricted Substance</b>	<b>Allowable Limit (at homogenous material level)</b>
Cadmium and its compounds	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its compounds	1000 ppm (0.1 weight %)
Lead and its compounds	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBB)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers (PBDE)	1000 ppm (0.1 weight %)

Parts/products exceeding the allowable limits at the homogeneous material level rely exclusively on the exemption(s) identified below:

- 7a. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
- 7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
- 7c-I. Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Signature:  
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